

Factorized Power Architecture

New Engines for Speed – Efficiency – Density





Quest for the Optimum Power Distribution Architecture

- Which power distribution architectures can efficiently support power systems from wall plugs, AC or DC outlets, through capacitors, super-capacitors or batteries, to processor cores – in the home, in the office, in the factory and everywhere in between?
 - Centralized Power Architecture (CPA)
 - Distributed Power Architecture (DPA)
 - Intermediate Bus Architecture (IBA)
 - Factorized Power Architecture (FPA)



Power Architecture Evolution





Centralized Power Architecture

Centralized power remains pervasive in smaller systems due to its simplicity and low cost

• But is unable to efficiently deliver high currents at low voltages



Power Architecture Evolution







Distributed Power Architecture

Distributed power addresses architectural limitations of CPA

- Provides efficient power distribution at higher voltages
- Puts bricks at the Point of Load (POL)
- But DPA comes at a price
 - Board real estate
 - System cost



Power Architecture Evolution





Intermediate Bus Architecture

Intermediate bus deals with the proliferation of load voltages

- Puts inexpensive non-isolated buck converters at the POL
- But IBA is limited by
 - Inability to transform V and I
 - Having to decrease a duty cycle to reduce output voltage
 - Inductive inertia standing in the way of dynamic loads



Power Architecture Evolution





Factorized Power Architecture

Factorized power addresses demanding POL current and voltage requirements:

- Puts a fast "current multiplier" at POL nodes
- Transforms V and I down to fractional POL voltages
- 100% effective duty cycle



IBA – Inherent Duty Cycle Limitations





FPA – No Duty Cycle Limitations





IBA – Inherent Step-Down Limitations





FPA – No Step-Down Limitations





IBA – Inherent Energy Storage & Dynamic Response Limitations





FPA – No Energy Storage or Dynamic Response Limitations





Energy Storage in the Wrong Place



Energy Storage in the Right Place





The Building Blocks of Factorized Power

- <u>V•I Chips (VICs)</u> "Full VIC" ~ 1.0 in² surface mount package
 - PRM Pre-Regulator Module
 - VTM Voltage Transformation Module





Basic FPA with PRM & VTM



- PRM <u>controls</u> the factorized bus voltage (V_f) to <u>regulate</u> the VTM output
- VTM transforms and isolates at the POL
- Combination: efficient distribution, regulation, transformation and isolation



FPA Example

Adaptive Loop with PRM



BOA



FPA Example

Independently Regulated Outputs





The Engine Under the Hood – PRM





"Full VIC" PRM Capabilities

- ZVS buck / boost regulator
- Input voltage: 1.5-400 V (up to 5:1 range)
- Step-up/step-down range: up to 5:1
- Output power: up to 300 W
- Conversion efficiency: up to 98%
- Frequency: up to 2 MHz



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PRM – ZVS Buck/Boost Engine



- ZVS buck-boost topology and control architecture
- High frequency operation



Power cycle comprises four conduction phases +In +In +Out
 1. Input phase Frequencies

Buck-Boost Control



 Power cycle comprises four conduction phases
 1. Input phase
 2. Input-output phase



Power cycle comprises four conduction phases
1. Input phase
2. Input-output phase
3. Free-wheeling phase



Power cycle comprises four conduction phases
1. Input phase
2. Input-output phase
3. Free-wheeling phase
4. Clamp phase



In VIC





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The Engine Under the Hood – VTM





"Full VIC" VTM Capabilities

- ZCS / ZVS Sine Amplitude Converter (SAC)
- Input voltage: 0-400 V (up to 2:1 range)
- Output voltage: 0-400 V
- Transformation ratio (K): 1/200 to 200
- Output current or power: up to 100 A or 300 W
- Conversion efficiency: up to 97%
- Conversion frequency: up to 4 MHz, fixed



VTM / BCM SAC Power Train



 Primary "Engine" is a Low Q oscillator formed by CRES and the leakage inductance of T1



VTM / BCM SAC Power Train



• The Low Q oscillator is driven by an H-bridge

NC3



VTM / BCM SAC Power Train



• In this particular example, secondary rectification is also performed using an H-bridge



VTM/BCM SAC Power Train



• Load current drives the Low Q oscillator by pulling primary current



VTM / BCM Sine Amplitude Converter (SAC)



• The amplitude of the Low Q oscillator is proportional to the load current as reflected back to the primary



VTM / BCM Level 2 Behavioral Model

48 V to 1.5 V 100 A VTM





VTM / BCM SAC Control



- The controller locks to the natural frequency of the Low Q oscillator and turns all switches ON and OFF under ZCS/ZVS conditions
- Conduction states result in a 100% effective duty cycle
- Control circuitry recycles the gate drive energy from each pair of switches



VTM / BCM SAC Control



- Control Servo locks to Sine Amplitude Converter resonant frequency and phase, compensating for power train parametric variabilities
- Soft start, inrush control and Adaptive Loop Compensation of Rout





VIDOI

BON





VIDIO

BON





VIDDA

NOM





VIDDI





VIDEN

BON



VTM / BCM SAC Engine – Additional Features

Bi-directional power transfer

Flexibility of topology





Common-mode cancellation





Superior System Performance

- Higher power/current density
 - Power conversion building blocks occupy less space
- Higher efficiency
 - Power conversion building blocks generate less heat
- Faster transient response
 - Overcomes processor/power technology gap
- Lower input and output noise
 - Reduced filtering frees up board space


SAC: Highest Power Density

- High fixed switching frequency (up to 4 MHz)
 - Reduces size of all reactive components
- Zero-current & zero-voltage switching (ZCS/ZVS)
 - Reduces stresses, losses and heat
- No serial energy storage
 - No output inductor
- 100% effective transformation duty cycle
 - Efficient power train utilization



From niPOLs to VICs



16 A / 80 W niPOL

- Surface mount
- Efficiency: 12 Vin to 1.2 Vout = 83%
- 1.30" x 0.53" x 0.37"
 (33,0 mm x 13,5 mm x 9,3 mm)
- Area: 0.7 in² (4,5 cm²)
- Volume: 0.25 in³ (4,1 cm³)



100 A / 300 W V·I Chip

- Surface mount
- Efficiency: 48 Vin to 1.2 Vout = 91%
- 1.26 " x 0.85" x 0.24"
 (32,0 mm x 21,5 mm x 6,0 mm)
- Area: 1.1 in² (6,9 cm²)
- Volume: 0.26 in³ (4,1 cm³)



From niPOLs to VICs



16 A / 80 W niPOL



100 A / 300 W V·I Chip





SAC: Highest Efficiency

- ZCS / ZVS
 - No switching losses
- Low Q transformer
 - Reduced winding losses
- No serial energy storage
 - No inductor losses
- 100% effective transformation duty cycle
 - Efficient power train utilization



Efficiency



VIDIO

BCM



Efficiency



VIDOI

0CM



SAC: Fastest Dynamic Response

- No serial energy storage & Low Q transformer
 - No current inertia & quick settling
- High fixed switching frequency (up to 4 MHz)
 - Minimal cycle-to-cycle delay
- Load independent control
 - No lag due to control loop
- Bi-directional power processing
 - Load dump energy recycled to input
- Capacitance multiplication
 - High effective POL capacitance: $Cout_{(eff)} \sim Cin \cdot (1/K)^2 + Cout$



Dynamic Response

K = 1/32 VTM @ Vout = 1 V



0 – 100 A load step with 100 μ F input capacitance and <u>NO</u> output capacitance



^{100 - 0} A load step with 100μ F input capacitance and <u>NO</u> output capacitance



SAC: Lowest Noise

- ZCS/ZVS
 - Order of magnitude reduction in *dl/dt*
 - Significant reduction in *dV/dt*
- Symmetric power train
 - Cancellation of common-mode noise
- High fixed switching frequency (up to 4 MHz)
 - Easy to filter



Output Noise

K = 1/32 VTM @ 1.0 V & 100 A



Output voltage ripple @ 100 A with <u>NO</u> bypass capacitance



Output voltage ripple @ 100 A with 200 µF ceramic bypass capacitance and 20 nH distribution inductance



The Flexibility of FPA

- Most contemporary power systems are a hybrid of centralized, distributed and intermediate bus
- Factorized power building blocks support existing power distribution architectures



V-I Chip Package Flexibility



Surface mount BGA package for in-board mounting



Surface mount J-Lead package for on-board mounting



Surface mount extended J-Lead package for on-board mounting



Intermediate Bus

- VTMs function as intermediate bus converters (BCMs)
- More power and more performance in less space





Distributed Power

- A PRM and VTM pair can replace bricks
- Superior performance at less cost





VICBrick – Up to 100 A in a 0.25" High Quarter-brick Package





Centralized Power

- PRMs can be remotely located
- Low current factorized buses can be easily routed throughout the system





From the Wall Plug to the Processor Core

150 – 200 Watt FPA Solution



Conventional Power System Architecture 12 V Intermediate Bus





12 V Input PRM/VTM Sub-system





Advanced Processor FPA System





Comparative Benchmark

	Conventional Pentium 4 Power System	12 V Input PRM / VTM Sub-System	Advanced Processor FPA System
Front-end			
Efficiency	86%	86%	91%
Power dissipation	18 W	18 W	11 W
Power density	6.6 W/in ³	6.6 W/in ³	25 W/in ³
POL (processor)			
Efficiency (1.2V @ 80 A)	87%	89%	93%
Power dissipation	14 W	12 W	7 W
Power density	23 W/in ³	59 W/in ³	120 W/in ³
Total (without auxiliary outputs)			
Efficiency	75%	77%	85%
Power dissipation	32 W	30 W	18 W
Power density	3.2 W/in ³	3.3 W/in ³	11.5 W/in ³



Power Architecture Evolution

Centralized Power (CPA)



Intermediate Bus (IBA)

Factorized Power (FPA)



Which is the Future?









FPA & V-I Chips Power Paradigm of the Future



Questions?